

REV LTR	DESCRIPTION	DATE	APPVD.
A	Para. 6, Changed Frequency Accuracy Options to Overall Frequency Accuracy Options that include 5 year aging.	4/15/22	MLG
B	Deleted Model XD8H, Updated Pages 8 & 9, Added Paras. 3.8, 3.9 & 3.10. Revised Para. 3.7.4	7/05/22	SPG
C	Added Reduced QCI Models on page 1	8/20/22	MLG

XSIS XD8S SERIES
LVDS OSCILLATORS
FOR SPACE & HI-REL APPLICATIONS
75 MHz to 200 MHz
(5 x 7 mm, SMD, 2.5V & 3.3V)

(Refer to Page 5 for Reduced QCI Models XD8E, XD8B & XD8P)

REV STATUS OF SHEETS	REV																
	SHEET NO.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
APPROVALS	DATE	XSIS ELECTRONICS, INC.															
PREP. N. Gupta	5/15/23	12620 W. 63 rd Street, Shawnee, KS 66216 USA															
ENG. M. Gupta	5/15/23	XD8S SERIES LVDS OSCILLATORS															
Q. A. S. Gupta	5/15/23																
CUST. ENG.		FSC NO. 57051						DWG. NO. XD8S									
CUST Q A.		SCALE N/A						SHEET 1 OF 9									

1. SCOPE:

XD8S, LVDS series, high reliability hybrid microcircuit crystal oscillators are designed, produced and tested by Xsis Electronics, Inc. as MIL-PRF-55310, Class "S" equivalent devices for use in advanced industrial, military, avionics and space applications. These devices are of hybrid microcircuit technology conforming to MIL-PRF-55310, Type 1, Class 2 oscillators.

1.1 ALTERNATE MODELS: Models XD8E, XD8B and XD8P with reduced QCI and/or reduced screening and shorter lead times are also offered as explained on page 5.

2. APPLICABLE DOCUMENTS:

MIL-PRF-55310F Oscillator, Crystal Controlled, General Specifications for
MIL-PRF-38534K Hybrid Microcircuits, General Specifications for
MIL-STD-883L Test Methods and Procedures for Microelectronics

3. REQUIREMENTS:

3.1 General: The individual item requirements shall be as specified herein.

3.2 Package: Ceramic, 90% Min. Al₂O₃, Weight 0.4 g Max., Thermal Resistance, θ_{JC} : 40°C / Watt.

3.2.1 Termination Finish: 1.27 μ m minimum gold plate over nickel. Hot Solder tinning with Sn63/Pb37 solder per MIL-PRF-55310 is optional at an additional cost.

3.2.3 Reflow Soldering: Reflow soldering at 260°C for 10 seconds shall not degrade the performance.

3.3 Hermeticity: Resistance welded, hermetically sealed, leak rate of $1 \times (10)^{-8}$ atm-cc/s Max.

3.4 Marking: As a minimum, the parts shall be marked with Xsis P/N, ESD symbol, date code and serial number.

3.5 Absolute Maximum Ratings: Unless otherwise specified, absolute maximum ratings shall be as follows:

Supply Voltage	-0.5 to +4.5 VDC
Operating Free-Air Temperature Range	-55°C to +125°C
Storage Temperature	-55°C to +125°C

3.6 Electrical Characteristics: See Table I

3.6.1 Total Dose Radiation: Hybrid Microcircuit Crystal Oscillators shall be capable of meeting the electrical characteristics of Para. 3.6 after being exposed to total ionizing dose radiation of 100 krad as per MIL-STD-883, method 1019.

3.7 Hybrid Elements:

3.7.1 Quartz Crystals: High grade cultured quartz crystal shall be used. As an option, Xsis will use premium Q swept quartz crystal at an additional charge, refer to part numbering example in paragraph 6 to specify swept quartz crystal. Crystal element evaluation shall be in accordance with MIL-PRF-55310.

3.7.2 Crystal Mounting: Crystal element shall be mounted at 4 points in such a manner as to provide adequate ruggedness and performance under extreme environments specified herein.

3.7.3 Passive Elements: Established Reliability (ER) QPL components, failure level R minimum shall be used or element lot evaluation shall be as per MIL-PRF-55310, class S, or MIL-PRF-38534, Appendix C, Class K as applicable.

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- 3.7.4 The microcircuit die shall be from lots that have passed the element evaluation per MIL-PRF-38534, Level K. In addition, ionizing radiation testing shall be performed at the oscillator level as explained in paragraph 3.7.5 herein.
- 3.7.5 The Microcircuit die shall be from wafer lots that have been successfully tested in the oscillator for ionizing radiation up to 100 krads. Xsis Electronics has also performed SET & SEL on the microcircuit die. The die is SEL immune for LET of up to 95 Mev-cm²/mg. Test reports are available on request.
- 3.7.6 Workmanship: Rework and Process controls shall be in accordance with the requirements of MIL-PRF-55310 & MIL-PRF-38534 as applicable.
- 3.7.7 Lot Traceability: Production lot for these oscillators shall be homogenous. Each element used in the production lot shall be traceable to a single lot. Swept quartz shall be traceable to the quartz bar, and its applicable processing details.
- 3.7.8 Prohibited Materials: The following items shall not be used in these oscillators: Pure Tin (Sn >97%), Cadmium, Zinc, Mercury, Selenium, Silver as under plate. Gold Plating without a nickel barrier.
- 3.7.9 Element Derating: All active and passive elements shall be derated in accordance with the applicable hybrid microcircuit requirements of MIL-STD-975. Elements shall not operate in excess of derated values.
- 3.7.10 Material Outgassing: All materials shall meet a TML of 1% Max. and a CVM of 0.1% Max., when tested in accordance with ASTM E595.
4. QUALITY ASSURANCE PROVISIONS: The quality assurance provisions shall be as specified herein.
- 4.1 100% Screening: The 100% screening shall be performed as per Table II. In addition, MIL-PRF-38534 Group B Option 1 in-line inspection for bond strength and die shear shall be performed at pre-seal inspection. PDA requirements for nondestructive bond pull and burn-in shall be as specified below.
- 4.2 PDA for Nondestruct Bond Pull: Unless otherwise specified, PDA shall be 2% of total number of wires or 1 wire whichever is greater.
- 4.3 PDA for Burn-in: Unless otherwise specified, PDA for burn-in shall be 2% or 1 oscillator whichever is greater and shall be applicable to +23°C to +25°C static tests only. In addition Delta Calculation shall be performed after Burn-in and shall count for PDA. All measured values for Delta Calculation shall be recorded. Parts that exceed the specified delta limits shall be rejected and be counted for PDA. Delta Calculation shall be performed at 2.5 VDC or 3.3 VDC, as applicable, for the following parameters:
- | | |
|-------------------|--------------------|
| Input Current | 10% change Maximum |
| Output High Level | 10% change Maximum |
| Output Low Level | 10% change Maximum |
- 4.4 Group A inspection shall be in accordance with MIL-PRF-55310 for product level S.
- 4.5 Group B inspection (30 day aging) shall be in accordance with MIL-PRF-55310 for product level S. In order to expedite delivery, by customer request, the aging test can be ended after 15 days if the amount of frequency aging is less than 50% of the 30 day specification limit.
- 4.6 Oscillators shall be capable of meeting group C inspection per MIL-PRF-55310. Generic group C inspection data on similar parts may be used to satisfy this requirement. When specified by the Customer, Xsis Electronics will perform Group C testing at an additional charge.

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4.7 Inspection and Test Data: Unless otherwise specified in the purchase order, the following Inspection and test data documentation shall be supplied with the parts.

(See Page 5 for the description of the Model Numbers other than XD8S)

Model XD8S:

Certificate of Conformance
Summary of Screening Test Results per Table II
PDA Calculations for Non-Destruct Bond Pull and Burn-in
Summary of Elements Lot Traceability
Electrical Tests before and after Burn-in
Group A Inspection Summary
Group B (30 day Aging) Data
Radiographic Inspection Certificate

Model XD8E:

Certificate of Conformance
Summary of Screening Test Results per Table III
Summary of Elements Lot Traceability
Group A Inspection Summary
Radiographic Inspection Certificate.

Model XD8B:

Certificate of Conformance
Summary of Screening Test Results per Table III
Group A Inspection Summary
Radiographic Inspection Certificate, if required by the Purchase Order, at additional cost

Model XD8P:

Certificate of Conformance

4.8 The following test and inspection options are available at customer request, at additional cost.

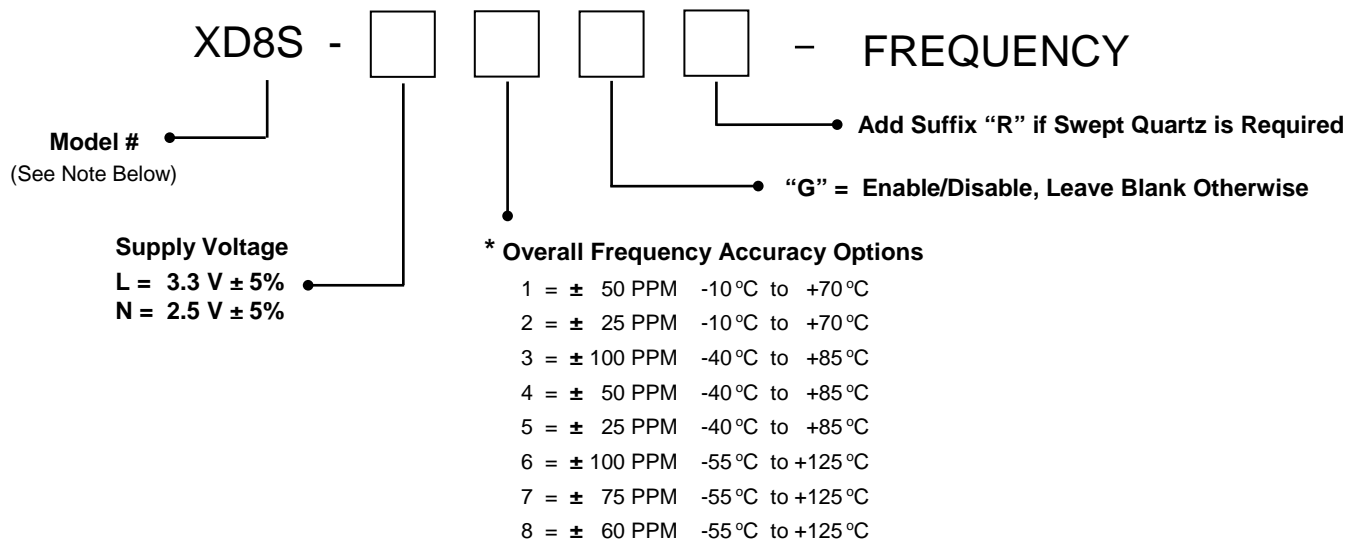
Customer Source Inspection for Pre-Cap and Final
Group C Inspection per MIL-PRF-55310 on 4 or 8 units
DPA (Destructive Physical Analysis)
Life Test per MIL-STD-883, Method 1005, 1000 Hrs. at +125°C
MIL-PRF-38534, Group B Inspection
MIL-PRF-38534, Group C Inspection

5.0 PRESERVATION, PACKAGING AND PACKING:

The oscillators shall be clean, dry and packaged in a manner to provide adequate protection against electrostatic discharge, corrosion, deterioration and physical damage during shipment.

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6. PART NUMBERING EXAMPLE:



* Overall Frequency Accuracy includes effects of Operating Temperature, Supply Voltage, Load variations and 5 year aging

P/N Example: XD8S- L8 -100.000 MHz = 100.000 MHz, 3.3V Oscillator, ± 60 PPM Overall Frequency Accuracy over operating temperature range of -55°C to +125°C,

NOTE: Besides Model XD8S above, the following additional models are available for applications that can accommodate reduced level of Elements, Screening and Quality Conformance inspection:

XD8E: Model XD8E uses the same design & elements as **Model XD8S** except as follows:

- 100% screening is as per Table III herein
- PDA for Burn-in is 10% or 1 unit whichever is greater
- Delta measurements of paragraph 4.3 are not applicable
- Group A inspection is as per MIL-PRF-55310, Class B
- Group B inspection (30 day aging) per MIL-PRF-55310 is not applicable

XD8B: Model XD8B is same as **Model XD8E** except as follows:

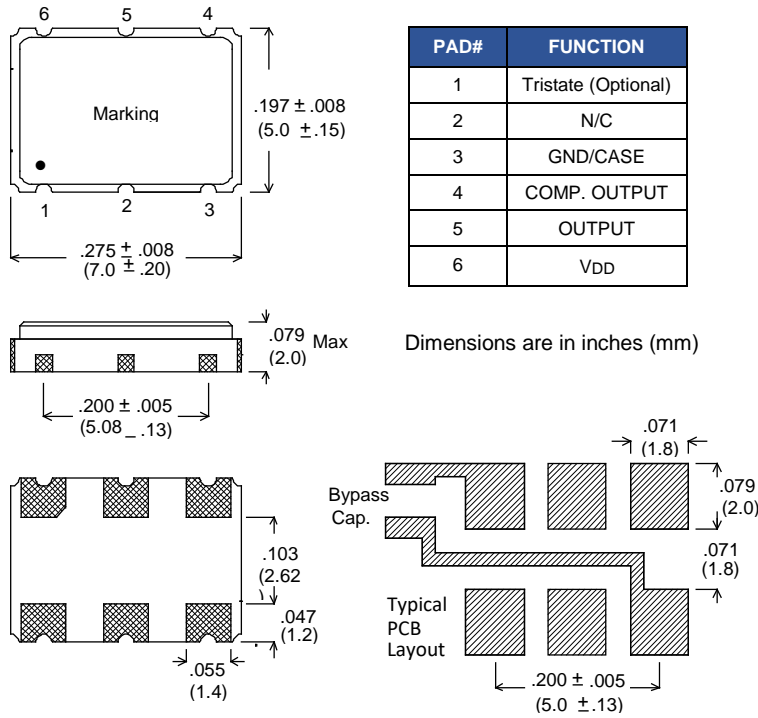
- Active and Passive Elements are as per MIL-PRF-55310, Class B. Microcircuit die is similar to the one used in Model XE8S but is not from radiation tested wafer lot.
- Radiographic Inspection is not applicable, unless required by the Purchase Order at additional cost.

XD8P: Model XD8P is a form, fit and function equivalent prototype of **Model XD8S**.

- Prototypes may use commercial grade elements and are not screened.
- Quality Conformance inspection is not applicable.

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7. PACKAGE OUTLINE:



Tristate Input: A "Low" level at the input disables the Output into a high impedance state. Tristate Input has internal pull-up.

An External 0.01uF Bypass Capacitor is required between VDD and GND.

Figure 1 - Package Configuration & Pin Connections

Table I – Electrical Characteristics for 2.5 V & 3.3V

Parameter	Spec. Limits
Frequency Range	75 MHz to 200 MHz
Overall Frequency Accuracy ^{1/}	See Options in Paragraph 6.0
Operating Temperature Range	See Options in Paragraph 6.0
Supply Voltage	See Options in Paragraph 6.0
Input Current (No Load)	65 mA Max.
Output Waveform	Square Wave
Output Duty Cycle	55/45% Max
Output Load	100 ohm across outputs
High Output Level	1.45V typical, 1.60 V Max.
Low Output Level	1.10V typical, 0.90 V Min.
Differential Output Voltage (Peak to Peak)	340 mV typical, 247 mV Min., 454 mV Max.
Offset Voltage	1.25 V typical, 1.125 V Min., 1.375 V Max.
Offset Error	50 mV Max.
Rise & Fall Times (20% to 80% Levels)	600 pS Max. over -55°C to +105°C 700 pS Max. over +105°C to +125°C
Tristate Input	> 0.7 Vdd or Open: Normal Output < 0.3 Vdd: High Impedance
Start-up Time	10 mS Max.
Phase Jitter	0.3 pS rms typ, (10 KHz to 20 MHz Integrated)
Frequency Aging @ 70°C	
≤ 150 MHz	± 1.5 PPM Max./30 days ± 5 PPM Max. first year, ± 2 PPM Max/year thereafter
> 150 MHz	± 2.0 PPM Max./30 days ± 6 PPM Max. first year, ± 2.5 PPM Max/year thereafter

^{1/} Frequency Accuracy with reference to nominal frequency includes initial accuracy at 25°C, ± 5% Supply Voltage and ± 10% load variations and 5 year aging.

Contact Xsis Engineering for any other special requirements.

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Table II - Model XD8S Screening (100%)

Test - Inspection	Test Method – Condition
Nondestructive Bond Pull	MIL-STD-883, Method 2023
Internal Visual	MIL-STD-883, Method 2017, Level S
Stabilization Bake (Prior to Seal) <u>1/</u>	MIL-STD-883, Method 1008, Condition C (+150°C) 48 hours minimum
Random Vibration	MIL-STD-883, Method 2026, Condition I- B
Thermal Shock	MIL-STD-883, Method 1011, Condition A
Temperature Cycling	MIL-STD-883, Method 1010, Condition C
Constant Acceleration	MIL-STD-883, Method 2001, Condition A Y ₁ axis only (5000 G)
Seal (Fine and Gross Leak) <u>2/</u>	MIL-PRF-55310, Para. 4.8.2.2.3
Particle Impact Noise Detection (PIND)	MIL-STD-883, Method 2020, Condition A
Radiographic Inspection	MIL-STD-883, Method 2012, Class S
Pre Burn-in Electrical Tests: Record as applicable	Refer to Table II-a below
Burn-in	+125°C, Nominal Supply Voltage and Burn-in load 320 Hours Minimum
Post Burn-in Electrical Tests: Record as applicable	Refer to Table II-a below
External Visual	MIL-STD-883, Method 2009

1/ Vacuum bake and maintain oscillators in dry nitrogen per MIL-PRF-55310.

2/ Fine & Gross leak test is also performed per MIL-PRF-55310, Para. 4.8.2.2 after lead forming operations.

Table II-a – Pre & Post Burn-in Electrical Tests

Test Parameter	MIL-PRF-55310 Method	Pre BI 24 ± 1°C	Post BI 24 ± 1°C	Post BI Low Temp	Post BI High Temp
Input Current	4.8.5	✓	✓	✓	✓
Output Frequency	4.8.6	✓	✓	✓	✓
Frequency Vs. Temperature Stability	4.8.10.1	✓	✓	✓	✓
Frequency Vs. Supply Voltage	4.8.14	✓	✓	✓	✓
Output Voltage Levels	4.8.21.3	✓	✓	✓	✓
Output Rise & Fall Times	4.8.22	✓	✓	✓	✓
Output Duty Cycle	4.8.23	✓	✓	✓	✓
Start-up time	4.8.29	✓	✓	✓	✓
Tristate, if applicable	4.8.28	✓	✓	✓	✓

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Table III - Models XD8E & XD8B, Screening (100%)

Test - Inspection	Test Method – Condition
Nondestructive Bond Pull	MIL-STD-883, Method 2023
Internal Visual	MIL-STD-883, Method 2017, Level B
Stabilization Bake (Prior to Seal) <u>1/</u>	MIL-STD-883, Method 1008, Condition C (+150°C) 24 hours minimum
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Constant Acceleration	MIL-STD-883, Method 2001, Condition A Y ₁ axis only (5000 G)
Seal (Fine and Gross Leak)	MIL-PRF-55310, Para. 4.8.2.2.2
Particle Impact Noise Detection (PIND)	MIL-STD-883, Method 2020, Condition A
Radiographic Inspection (Model XD8E Only) <u>2/</u>	MIL-STD-883, Method 2012, Class S
Pre Burn-in Electrical Tests: Verify all measurements	Refer to Table III-a below
Burn-in	+125°C, Nominal Supply Voltage and Burn-in load 160 Hours Minimum
Post Burn-in Electrical Tests: Verify all measurements	Refer to Table III-a below
External Visual	MIL-STD-883, Method 2009

1/ Vacuum bake and maintain oscillators in dry nitrogen per MIL-PRF-55310

2/ Radiographic Inspection is applicable to Model XD8E only

Table III-a – Pre & Post Burn-in Electrical Tests

Test Parameter	MIL-PRF-55310 Method	Pre BI 24 ± 1°C	Post BI 24 ± 1°C	Post BI Low Temp	Post BI High Temp
Input Current	4.8.5	✓	✓	✓	✓
Output Frequency	4.8.6	✓	✓	✓	✓
Frequency Vs. Temperature Stability	4.8.10.1	✓	✓	✓	✓
Frequency Vs. Supply Voltage	4.8.14	✓	✓	✓	✓
Output Voltage Levels	4.8.21.3	✓	✓	✓	✓
Output Rise & Fall Times	4.8.22	✓	✓	✓	✓
Output Duty Cycle	4.8.23	✓	✓	✓	✓
Start-up time	4.8.29	✓	✓	✓	✓
Tristate, if applicable	4.8.28	✓	✓	✓	✓

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